



## **ASE and FlipChip International Sign Worldwide Licensing Agreement**

*License enables global implementation of wafer bumping technology and UltraCSP™ wafer-level packaging technology*

Santa Clara, California, April 28, 2005 – Advanced Semiconductor Engineering Incorporated (ASE, TAIEX: 2311, NYSE: ASX), the world’s largest semiconductor packaging and test company, and FlipChip International, LLC (FCI), the global leader in flip chip bumping and wafer level packaging technology, today announced they have signed an expanded technology licensing agreement. Under the agreement, ASE will expand its manufacturing capabilities through the worldwide implementation of FCI’s wafer bumping technology and UltraCSP™ wafer-level packaging technology.

FCI’s wafer bumping technology offers complete solder paste bumping solutions for fine pitch devices, including 0.125mm pitch densities and below, while its UltraCSP™ technology addresses high reliability applications requiring JEDEC 1 capability in the smallest form factor available. Flip chip packaging and wafer level packaging are growing faster than standard semiconductor packaging due to substantial benefits attributable to cost, device size and performance. Both technologies can be readily implemented and integrated into existing equipment and process flows, while FCI will ensure fast ramp-up by immediately providing all necessary documentation, training and engineering support.

ASE has implemented the FCI wafer bumping technology since 2001. Through the provisions of FCI’s licensing agreement, ASE is now expanding its wafer bumping and UltraCSP™ technologies to customers worldwide and in all ASE manufacturing locations.

“We are pleased that ASE has chosen to implement our technologies worldwide, given its dominant presence as a global semiconductor packaging manufacturer, supplying the communication, consumer, and computing markets,” said Tom Strothmann, Vice President of New Business Development, FlipChip International. He continued, “This agreement with ASE recognizes the value of FCI’s Intellectual Property and confirms our position as a technology leader in flip chip and wafer level packaging. We place great value on the continued business and technology relationship with ASE as we demonstrate the economies and efficiencies of our technologies to the semiconductor industry.”

“With global demand for flip chip and wafer-level packages growing exponentially, the new

licensing agreement with FCI enables ASE to offer customers significant economic and performance advantages,” said Dr. Homing Tong, General Manager of Corporate R&D, ASE Group “Given that our customers are under enormous pressure to bring products to market quickly, ASE is driven by the need to provide the smoothest possible supply chain flow, while ensuring lower overall costs. Along with our rapidly-expanding global capacities, the agreement with FCI will address customer challenges through the provision of a complete flip chip turnkey solution, which we believe is the most optimal way to meet their needs.”

### **About FlipChip International**

FlipChip International, LLC is a recognized technology leader in products and services for the wafer bumping and wafer scale packaging semiconductor market. FCI’s licensed technology is used by the largest semiconductor assembly and test service providers worldwide. Flip Chip International, LLC is a wholly owned subsidiary of privately-held RoseStreet Labs, LLC, a supplier of products and services for wireless infrastructure in the life science, renewable energy and homeland security markets. For more information about FlipChip International, LLC, visit [www.flipchip.com](http://www.flipchip.com).

### **About ASE Group**

The ASE Group is the world's largest provider of independent semiconductor manufacturing services in assembly and test. As a global leader geared towards meeting the industry’s ever growing needs for faster, smaller and higher performance chips, the Group develops and offers a wide portfolio of technology and solutions including IC test program design, front-end engineering test, wafer probe, wafer bump, substrate design and supply, wafer level package, flip chip, system-in-package, final test and electronic manufacturing services through Universal Scientific Industrial Co. Ltd., a member of the ASE Group. The Group generated sales revenues of \$2.45 billion in 2004 and employs over 30,000 people worldwide. For more information about the ASE Group, please visit [www.aseglobal.com](http://www.aseglobal.com).

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